

## 40V N-SGT Enhancement Mode MOSFET

### General Description

APG120N04NF use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

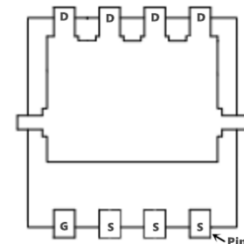
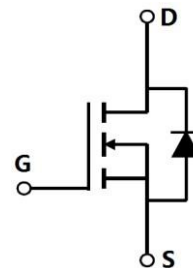
This device is specially designed to get better ruggedness and suitable to use in

### Features

- Low RDS(on) & FOM
- Extremely low switching loss
- Excellent stability and uniformity or Invertors

### Applications

- Consumer electronic power supply
- Motor control
- Synchronous-rectification
- Isolated DC
- Synchronous-rectification applications



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
APG120N04NF	PDFN5*6-8L	APG120N04NF XXX YYY	5000

### Absolute Maximum Ratings at T<sub>J</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	120	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	82	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	400	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	400	mJ
I <sub>AS</sub>	Avalanche Current	40	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	125	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	1	°C/W

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**Electrical Characteristics** at  $T_J=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	---	1.4	1.8	mΩ
		$V_{GS}=4.5V, I_D=20A$	---	2.0	2.6	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.2	V
IDSS	Drain-Source Leakage Current	$V_{DS}=32V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=32V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=20A$	---	53	---	S
Rg	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1.0	---	Ω
Qg	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=10V, I_D=20A$	---	45	---	nC
Qgs	Gate-Source Charge		---	12	---	
Qgd	Gate-Drain Charge		---	18.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=20A$	---	18.5	---	ns
Tr	Rise Time		---	9	---	
Td(off)	Turn-Off Delay Time		---	58.5	---	
Tf	Fall Time		---	32	---	
Ciss	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, f=1\text{MHz}$	---	3972	---	pF
Coss	Output Capacitance		---	1119	---	
Crss	Reverse Transfer Capacitance		---	82	---	
IS	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V, \text{Force Current}$	---	---	100	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2 .The data tested by pulsed , pulse width  $\cong 300\mu s$  , duty cycle  $\cong 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.5mH, I_{AS}=40A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5 .The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

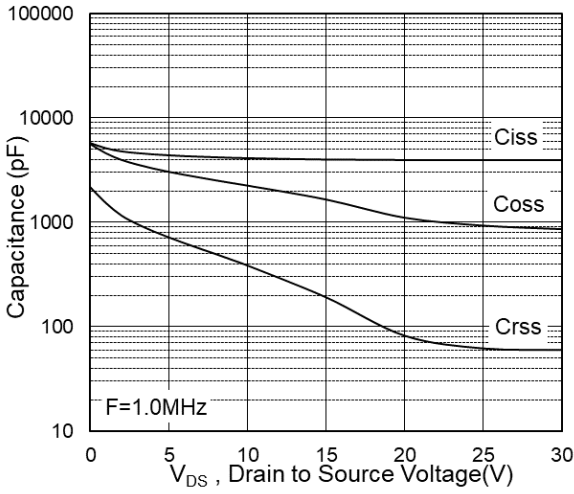


Fig.7 Capacitance

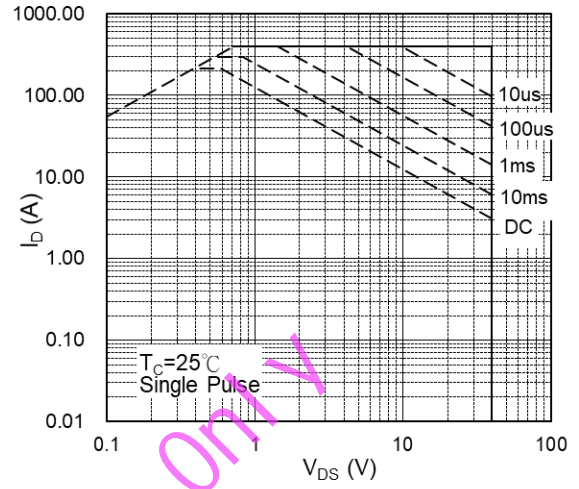


Fig.8 Safe Operating Area

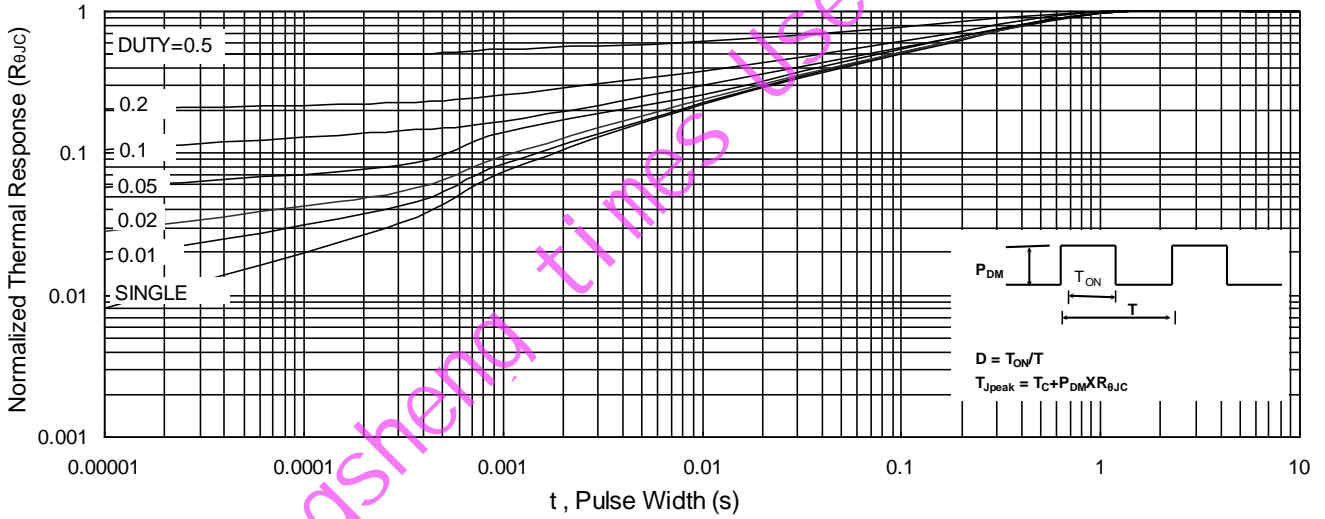


Fig.9 Normalized Maximum Transient Thermal Impedance

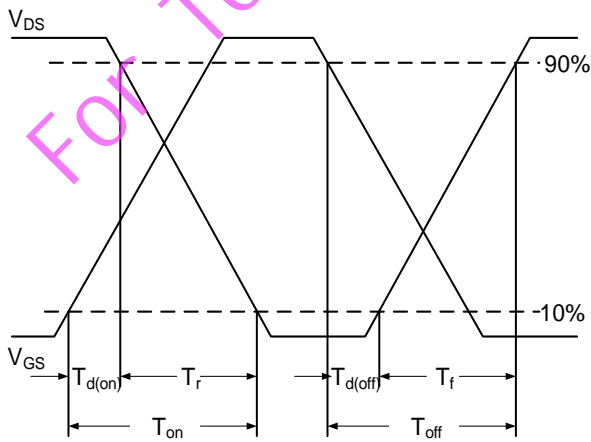


Fig.10 Switching Time Waveform

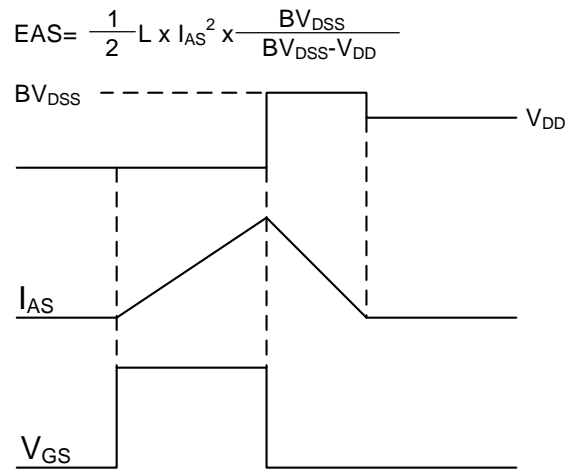
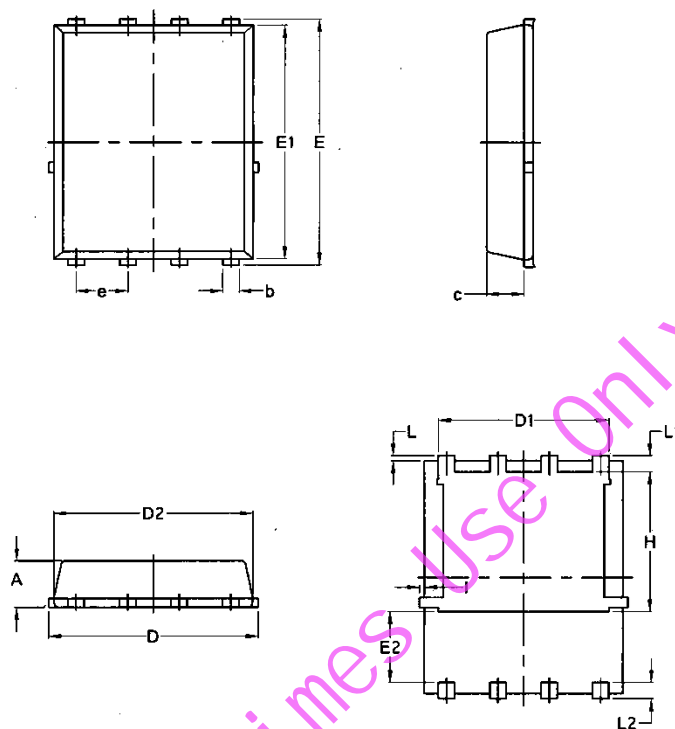


Fig.11 Unclamped Inductive Switching Waveform

### Package Mechanical Data-DFN5\*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

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